

NEW

バリスタ基板 CeraPad™

CeraPad™ substrate

ESD保護機能内蔵のLEDパッケージ用セラミック基板

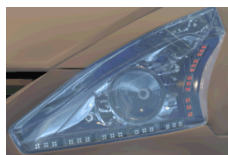
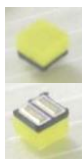
LED carrier with integrated ESD protection

Features

- >22W/mKの高熱伝導性セラミックス
High thermal conductivity of min. 22 W/mK
- 30kVの高ESD耐性
Integrated ESD protection up to 30 kV
- 基板内部に10層まで内部回路を形成可能
Up to 10 routing layers for matrix modules

Applications

- LED パッケージ
Chip Scale Package (CSP) LEDs
- フラッシュモジュール
LED flash modules
- LED アダプティブヘッドライト
Matrix LED for adaptive headlights of cars

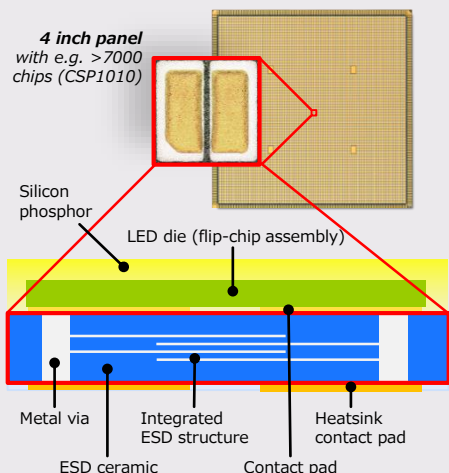


Characteristics

CeraPad™ wafer-level CSP

Smaller, thinner LED Packages inkl. full ESD protection

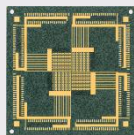
4 inch panel with e.g. >7000 chips (CSP1010)



CeraPad™ matrix LED platform

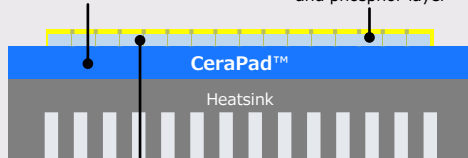
Offers the **most flexible** platform for **high resolution, ultra compact, LED matrix modules** with **reliable thermal conductivity**

- Customer-specific substrate design
- Cost effective and energy efficient solution due to the compact design possibilities



CeraPad functions as **LED carrier** and **3D circuit board** (up to routing 10 layer) incl. ESD protection

CSP LED/ LED die and phosphor layer



High LED density with minimum gap for LEDs down to **CSP0707** and up to 1.5 W/LED